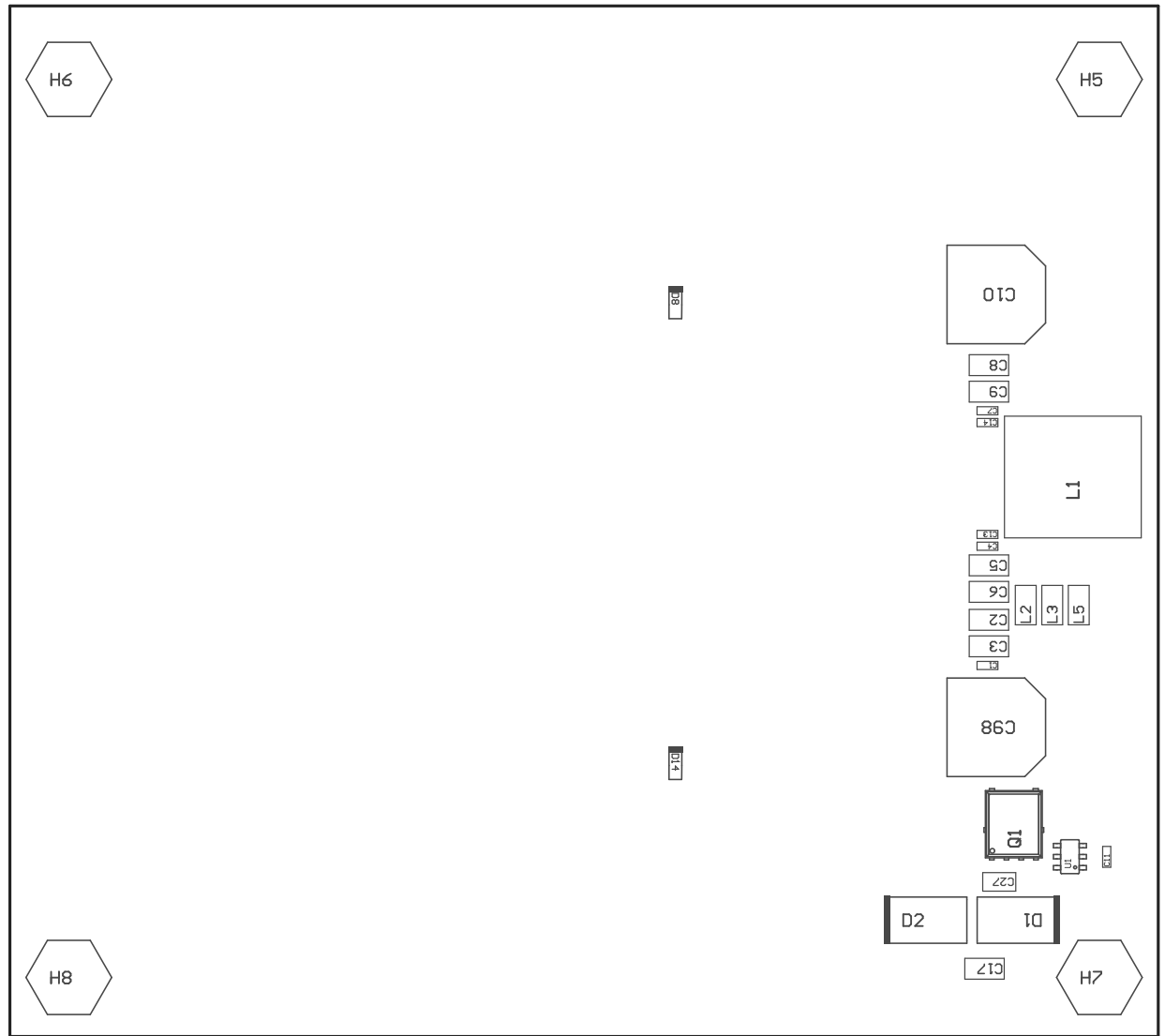


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP21096	REV: C	SUN REV: Not In VersionControl
	TID #: PMP21096		
PLOT NAME = Top Assembly Drawing	GENERATED : 4/11/2018 6:55:03 AM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP21096	REV: C	SVN REV: Not In VersionControl
	TID #: PMP21096		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/11/2018 6:55:05 AM		TEXAS INSTRUMENTS

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